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BASIC PRINCIPLES

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The influence of PCB, package and system design on shielding effectiveness, basic physical effects and parameters, emission and immunity requirements, standards and how to meet them with shielding materials provide the reader with a basic knowledge of electromagnetic shielding.

COMPONENTS

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The second part describes the various shielding materials, their characterization, and valuable information on material compatibility, compression force and assembly.

APPLICATIONS

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This chapter provides practical guidance on the use of shielding materials in applications such as wireless power, board-level shielding, NFC and RFID.

TIPS FOR EMI SHIELDING DESIGN

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The final chapter provides a comprehensive overview with practical tips on the selection and use of shielding materials.

APPENDIX

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The book concludes with a bibliography and suggestions for further reading.